

Please add the following new claims:

7. The packaged integrated circuit of Claim 1 wherein the protective film includes plastic.

8. The packaged integrated circuit of Claim 1 wherein the protective film includes epoxy.

9. The packaged integrated circuit of Claim 1 wherein the protective film includes laser identification markings.

10. The packaged integrated circuit of Claim 1 wherein the protective film is non-metallic.

11. A packaged integrated circuit device comprising:
a die having a plurality of electrical contacts disposed on a first surface of the die; and
a protective film adhered directly to a back surface of the die, opposite the first surface, the protective film being thick enough to allow laser marking of the protective film without the laser penetrating to the die,
wherein the protective film has a thickness between about 1.5 and 5 mils and includes laser identification markings.

12. The packaged integrated circuit device of Claim 11 wherein the protective film includes epoxy.

13. The packaged integrated circuit device of Claim 11 wherein the protective film includes plastic.

10022583-121701

14. The packaged integrated circuit device of Claim 11 wherein the protective film is substantially co-extensive with the back surface.

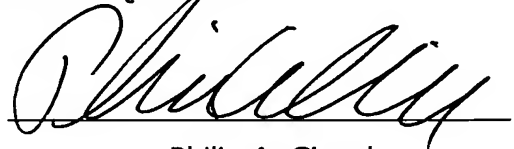
15. The packaged integrated circuit device of Claim 11 wherein the electrical contacts include a plurality of contact bumps.

Respectfully submitted,

GIRARD & EQUITZ LLP

Dated: 11/15/01

By:



Philip A. Girard
Reg. No. 28,848

Attorneys for Applicant(s)

Attorney Docket No. NSC1-G9900

10022583-121701